

Description

The SX30P10NF uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS} = -100V$ $I_D = -30A$

$R_{DS(ON)} < 95m\Omega$ @ $V_{GS}=10V$

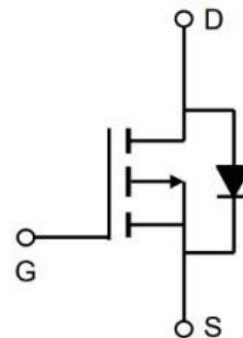
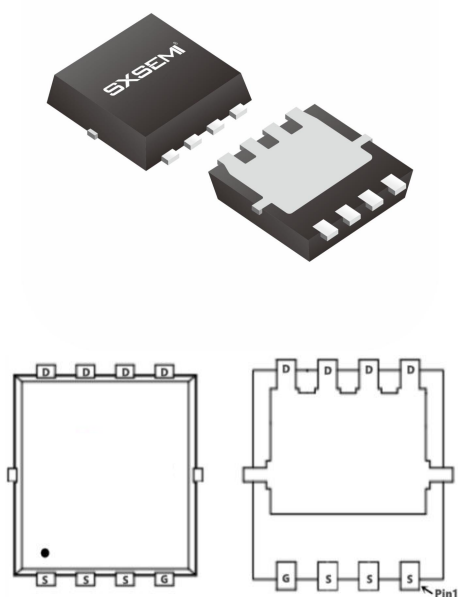
Application

Brushless motor

Load switch

Uninterruptible power supply

PDFN5*6-8L



Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-100	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_c=25^\circ C$	Continuous Drain Current, V_{GS} @ -10V ¹	-30	A
$I_D @ T_c=100^\circ C$	Continuous Drain Current, V_{GS} @ -10V ¹	-18	A
I_{DM}	Pulsed Drain Current ²	-90	A
EAS	Single Pulse Avalanche Energy ³	157.2	mJ
I_{AS}	Avalanche Current	-19	A
$P_D @ T_c=25^\circ C$	Total Power Dissipation ⁴	280	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	25	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	2.3	$^\circ C/W$

P-Channel Electrical Characteristics (T_J =25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-100	---	---	V
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-10A	---	68	95	mΩ
		V _{GS} =-4.5V , I _D =-8A	---	78	110	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-1.2	-1.7	-2.5	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-100V , V _{GS} =0V , T _J =25°C	---	---	-1	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V	---	---	±100	nA
g _{fs}	Forward Transconductance	V _{DS} =-10V , I _D =-10A	---	24	---	S
Q _g	Total Gate Charge	V _{DS} =-50V , V _{GS} =-10V , I _D =-20A	---	44.5	---	nC
Q _{gs}	Gate-Source Charge		---	9.13	---	
Q _{gd}	Gate-Drain Charge		---	5.93	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =-50V , V _{GS} =-10V , R _G =3.3 , I _D =-10A	---	12	---	ns
T _r	Rise Time		---	27.4	---	
T _{d(off)}	Turn-Off Delay Time		---	79	---	
T _f	Fall Time		---	53.6	---	
C _{iss}	Input Capacitance	V _{DS} =-20V , V _{GS} =0V , f=1MHz	---	3029	---	pF
C _{oss}	Output Capacitance		---	129	---	
C _{rss}	Reverse Transfer Capacitance		---	76	---	
I _S	Continuous Source Current ^{1,5}	V _G =V _D =0V , Force Current	---	---	-30	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25°C	---	---	-1.2	V
t _{rr}	Reverse Recovery Time	I _F =-8A , di/dt=-100A/μs , T _J =25°C	---	38.7	---	nS
Q _{rr}	Reverse Recovery Charge		---	22.4	---	nC

Note :

- 1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3、The EAS data shows Max. rating . The test condition is V_{DD} =-72V,V_{GS} =-10V,L=0.1mH,I_{AS} =-19A
- 4、The power dissipation is limited by 150°Cjunction temperature
- 5、The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

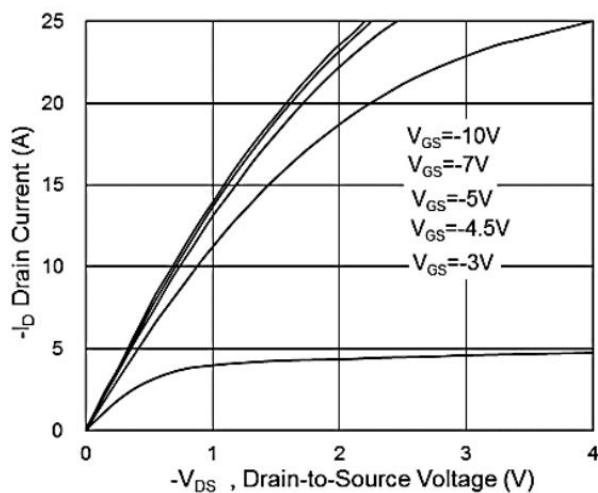


Fig.1 Typical Output Characteristics

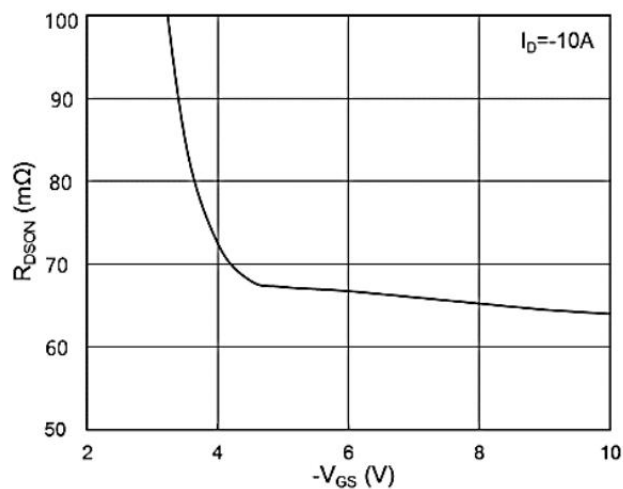


Fig.2 On-Resistance vs G-S Voltage

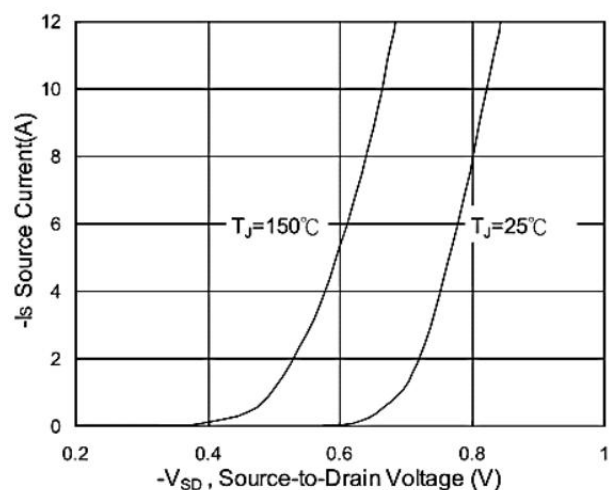


Fig.3 Typical S-D Diode Forward Voltage

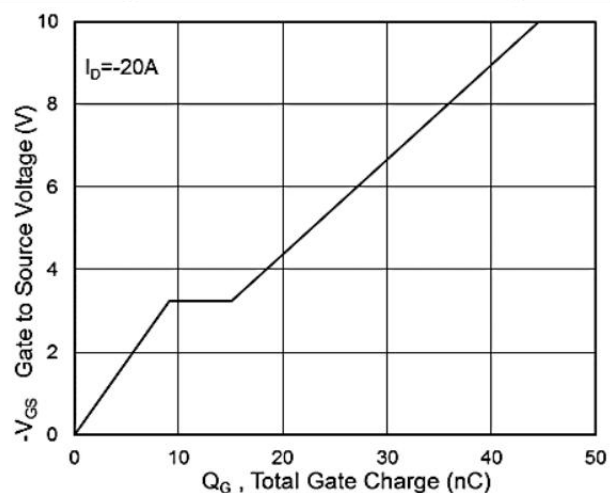


Fig.4 Gate-Charge Characteristics

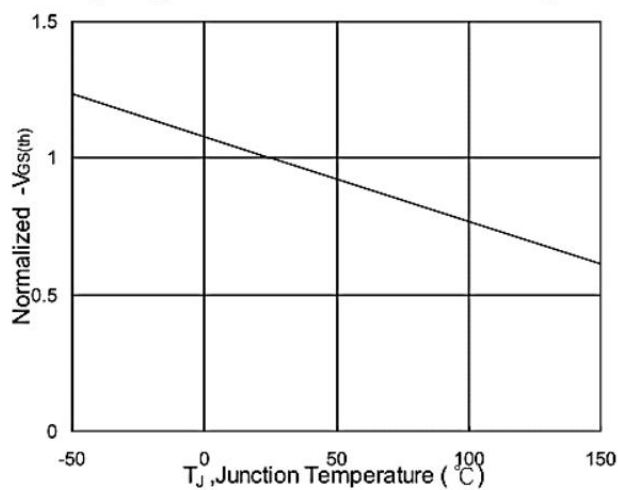


Fig.5 Normalized $V_{GS(th)}$ vs T_J

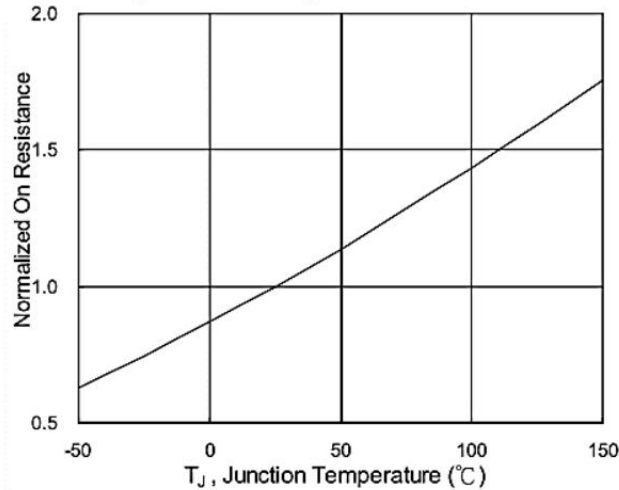
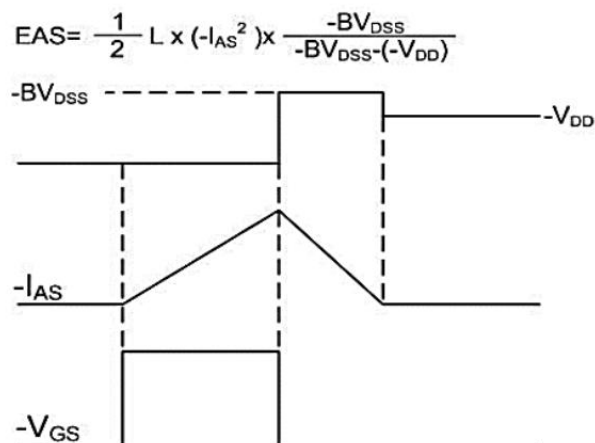
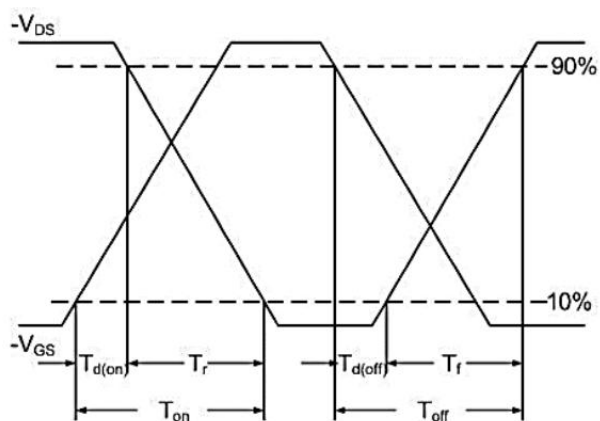
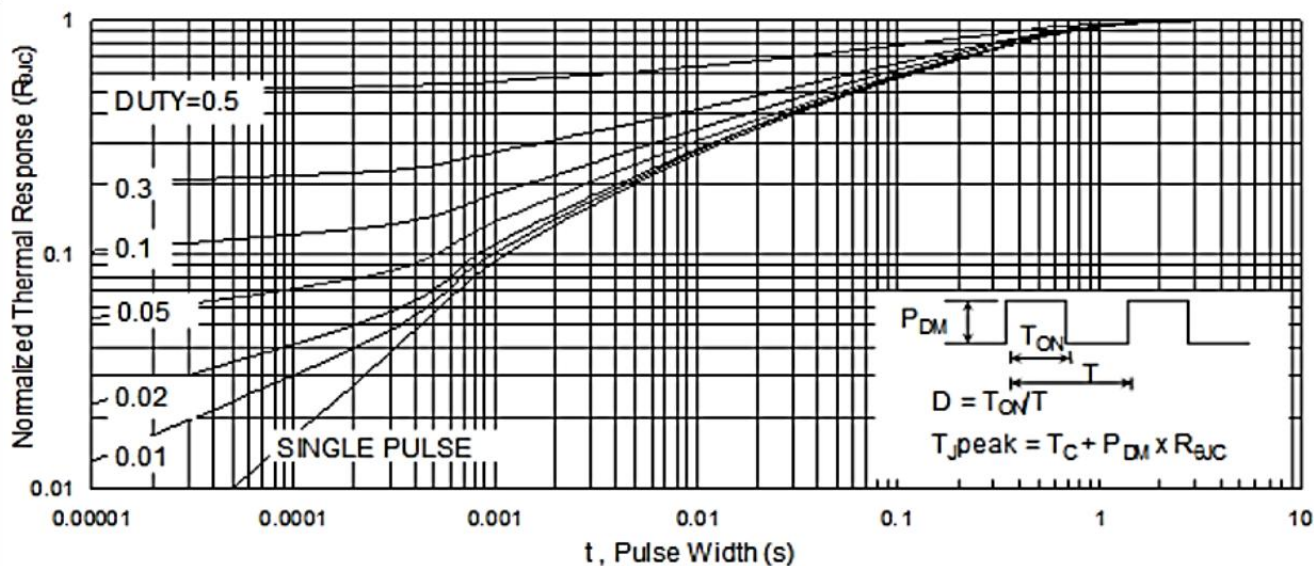
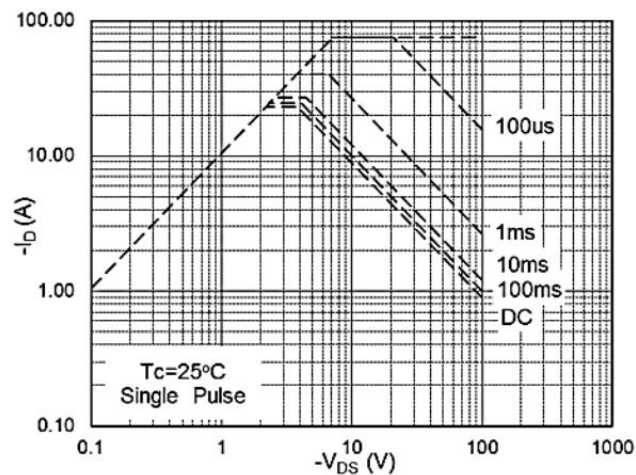
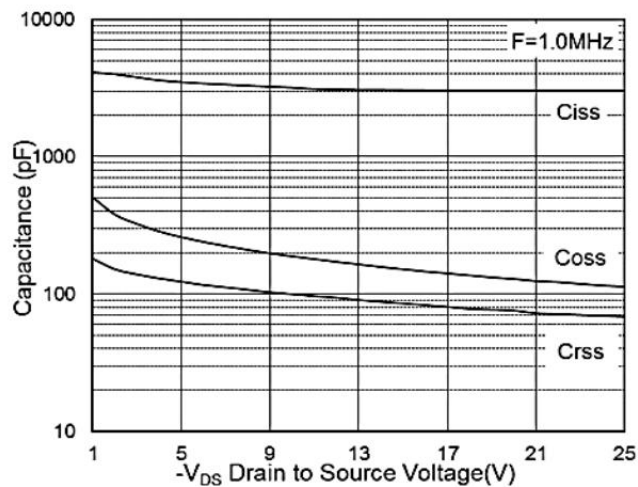
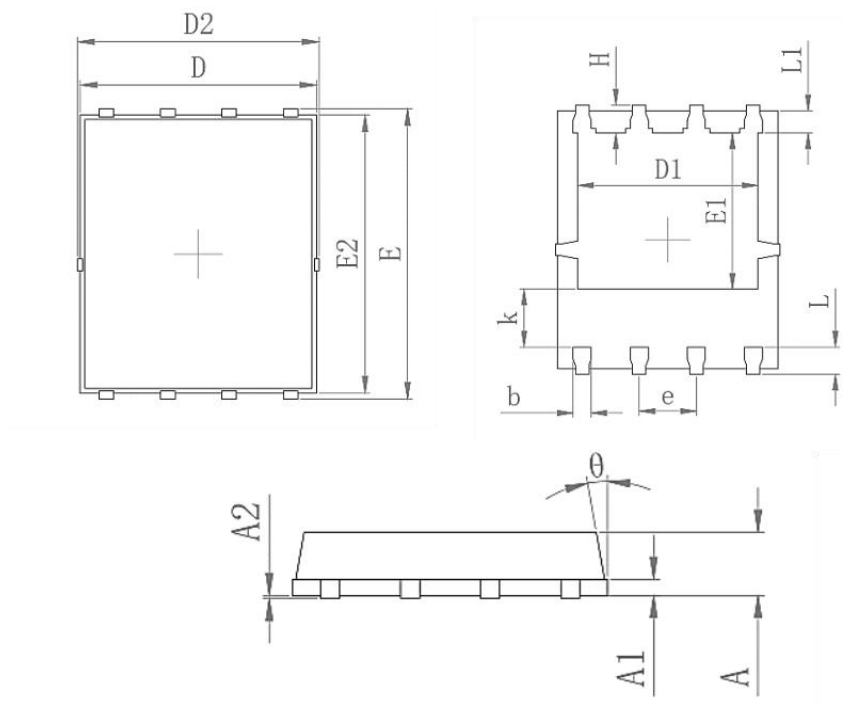


Fig.6 Normalized $R_{DS(on)}$ vs T_J

Typical Characteristics



Package Mechanical Data-PDFN5X6-8L-XZT Single



Symbol	Common	
	mm	
	Mim	Max
A	0.90	1.10
A1	0.254 REF	
A2	0-0.05	
D	4.824	4.976
D1	3.910	4.110
D2	4.944	5.076
E	5.924	6.076
E1	3.375	3.575
E2	5.674	5.826
b	0.350	0.450
e	1.270	
L	0.534	0.686
L1	0.424	0.576
K	1.190	1.390
H	0.549	0.701
Φ	8°	12°

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TAPING	PDFN5*6-8L		5000